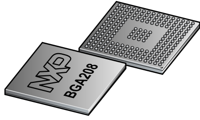

SOT1513-1

BGA208, plastic, ball grid array package; 208 balls; 1 mm pitch; 17 mm x 17 mm x 1.15 mm body

7 January 2019 — Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA208
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MO-151 AAF-1
Mounting method type	S (surface mount)
Issue date	08-03-2016
Manufacturer package code	98ARS23882W

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
package height	-	1.15	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	208	-	

2 Package outline

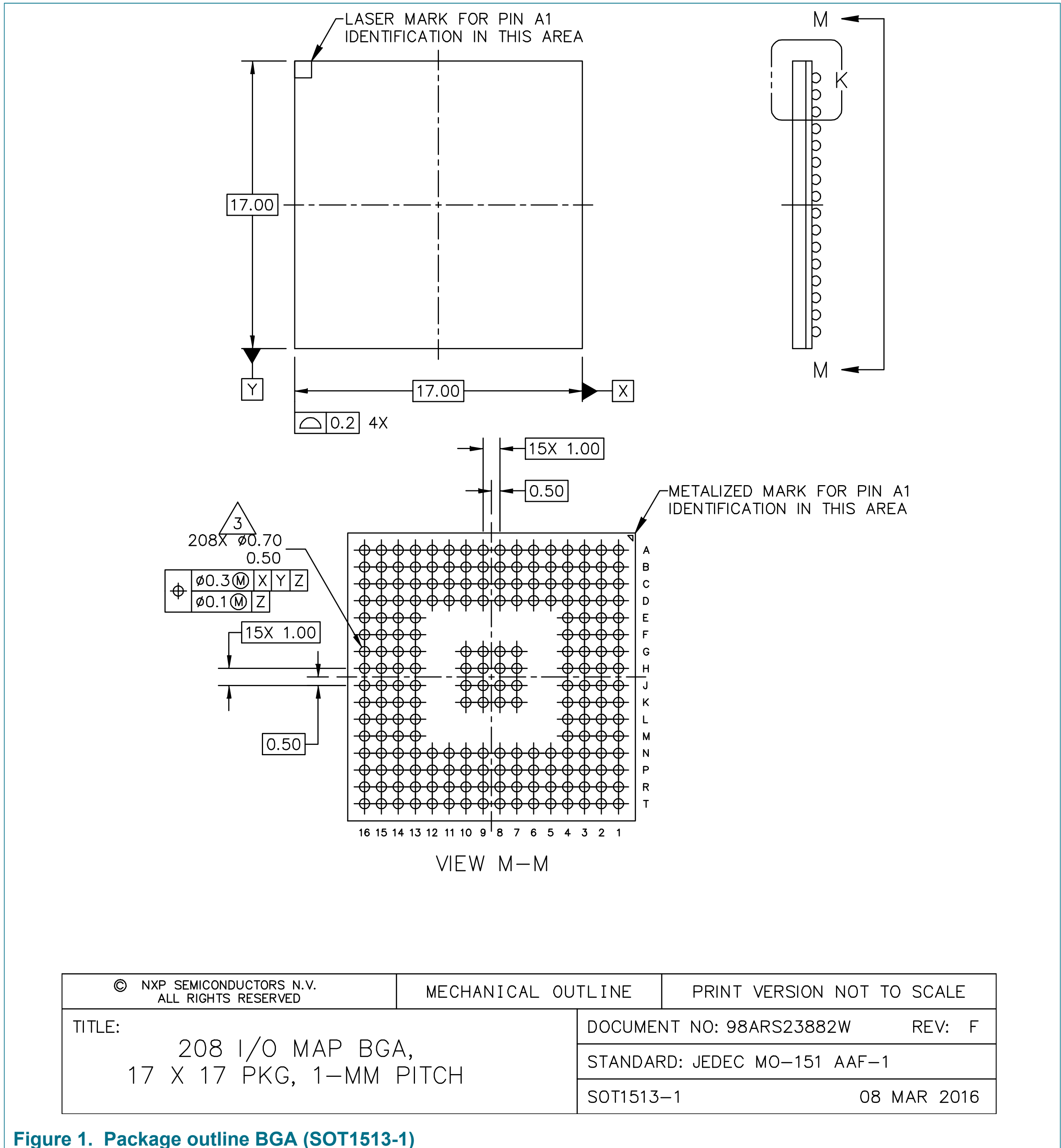

Figure 1. Package outline BGA (SOT1513-1)

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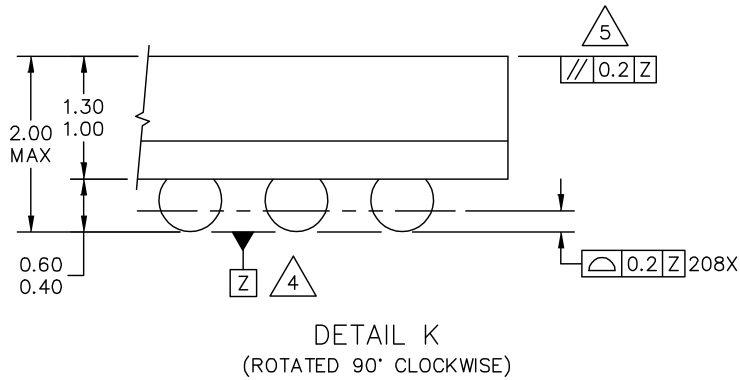

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TITLE: 208 I/O MAP BGA, 17 X 17 PKG, 1–MM PITCH	DOCUMENT NO: 98ARS23882W REV: F	
	STANDARD: JEDEC MO–151 AAF–1	
	SOT1513–1 08 MAR 2016	

Figure 2. Package outline dt1 BGA (SOT1513-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M—1994.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. PACKAGE CODE SUMMARY:
   MAP BGA: 5253
   MAP BGA PGE DIE: 5371

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TITLE: 208 I/O MAP BGA, 17 X 17 PKG, 1—MM PITCH	DOCUMENT NO: 98ARS23882W	REV: F
	STANDARD: JEDEC MO—151 AAF—1	
	SOT1513—1	08 MAR 2016

Figure 3. Package outline note BGA (SOT1513-1)

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3 Legal information

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